heat and coolness between said first component and said second component.

42. The method of claim 41, wherein the liquefying/dispersing temperature of said first component is greater than about 60°C, and wherein the liquefying/dispersing temperature of said second component is less than about 15°C.

43. The method of claim 41, wherein said first and said second components have a liquefying/dispersing temperature difference of at least about 10°C to about 85°C.

44. The method of claim 43, wherein the temperature difference is about 30°C to about 50°C.

45. The method of claim 41, wherein the liquefied/dispersed first component is placed into said molding apparatus at a temperature from about 70°C to about 90°C.

46. The method of claim 45, wherein the liquefied/dispersed second component is placed into said molding apparatus at a temperature from about -4°C to about 13°C.

47. The method of claim 41, wherein said first and said second components form discrete first and second segments of the composition upon being fully set-up.

48. The method of claim 41, further comprising blending said first and said second components before said first and said second components are fully set to create a marbleized composition.

49. The method of claim 41, wherein said first component has a wax base.

50. The method of claim 49, wherein said second component is wax-free.

51. The method of claim 50, wherein said second component is a smectite clay dispersed in a solvent.

52. The method of claim 47, wherein said molding apparatus forms said first and said second components in a core-sheath arrangement.

53. The method of claim 47, comprising

(a) inserting a hollow injector having a dispensing nozzle into a cavity of said molding apparatus;

(b) placing one of said first and said second components into said cavity to form a sheath at least partially about said injector;

(c) withdrawing said injector from said cavity to form a cavity core;

(d) dispensing the other of said first and said second components from said dispensing nozzle into said cavity core as said injector is withdrawn; and

(e) effecting said thermal exposure between said first and said second components.

54. The method of claim 47, comprising

(a) inserting a rod into a cavity of said molding apparatus;

(b) placing one of said first and said second components into said cavity to form a sheath at least partially about said rod;

(c) withdrawing said rod from said cavity to form a cavity core;

(d) placing the other of said first and said second components into said cavity core; and

(e) effecting said thermal exposure between said first and said second components.

55. The method of claim 47, comprising

(a) placing a solid hollow insert made of said first or said second component into a cavity of said molding apparatus;

(b) placing the other of said first and said second components different from said hollow insert into said cavity to form a sheath at least partially about said hollow insert;

(c) placing the other of said first and said second components into said hollow insert;

(d) at least partially liquefying or dispersing said hollow insert upon contact with said other of said first and said second components; and

(e) effecting said thermal exposure between said first and said second components.

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56. The method of claim 47, comprising

(a) placing a perforated, hollow insert made of said first or said second component into a cavity of said molding apparatus;

(b) placing one of said first and said second components different from said hollow insert into said cavity to form a sheath at least partially about said hollow insert;

(c) placing the other of said first and said second components into said hollow insert; and

(d) effecting said thermal exposure between said first and said second components.

57. The method of claim 47, comprising

(a) placing a solid hollow insert made of said first or said second component into a cavity of said molding apparatus;

(b) placing the other of said first and said second components different from said hollow insert into said cavity to form a sheath at least partially about said hollow insert;

(c) placing the other of said first and said second components into said hollow insert;

(d) at least partially sublimating said hollow insert upon contact with said other of said first and said second components; and

(e) effecting said thermal exposure between said first and said second components.

58. The composition of claim 35, wherein the liquefying/dispersing temperature of said first component is greater than about 60°C, and wherein the liquefying/dispersing temperature of said second component is less than about 15°C.

59. The composition of claim 35, wherein said first and said second components have a liquefying/dispersing temperature difference of at least about 10°C to about 85°C.

60. The composition of claim 59, wherein the temperature difference is about 30°C to about 50°C.

61. The composition of claim 35, wherein the first component is liquefied or dispersed and is placed into a molding apparatus at a temperature from about 70°C to about 90°C.

62. The composition of claim 61, wherein the second component is liquefied or dispersed and is placed into said molding apparatus at a temperature from about -4°C to about 13°C.

63. The composition of claim 35, wherein said first and said second components form discrete first and second segments of the composition upon being fully set-up.

64. The composition of claim 35, wherein the composition is marbleized.

65. The composition of claim 35, wherein said first component has a wax base.

66. The composition of claim 65, wherein said second component is wax-free.